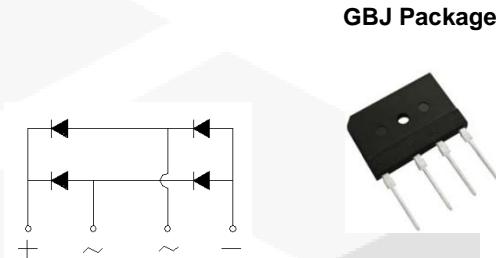


Single Phase Glass Passivated Silicon Bridge Rectifier

V_{RRM} = 100 V - 400 V
I_O = 25 A

Features

- Epoxy Resin material compliant with 94V-0 standards of UL Material Flammability Provisions
- Compliant with RoHS Provisions
- Single in-line DIP package, compact size
- Low forward voltage, high forward current
- High surge current capability
- Types from 100 V to 400 V V_{RRM}
- Small size, high heat-conducting performance
- Thermal welding performance: 260 °C/10 s
- Weight: 7.25 g (0.25 Oz)
- Not ESD Sensitive



Maximum ratings at T_A = 25 °C (ambient temperature), unless otherwise specified

Parameter	Symbol	Conditions	GBJ25B	GBJ25D	GBJ25G	Unit
Repetitive peak reverse voltage	V _{RRM}		100	200	400	V
DC blocking voltage	V _{DC}		100	200	400	
Operating temperature	T _j		-50 to 150	-50 to 150	-50 to 150	°C
Storage temperature	T _{stg}		-50 to 150	-50 to 150	-50 to 150	°C

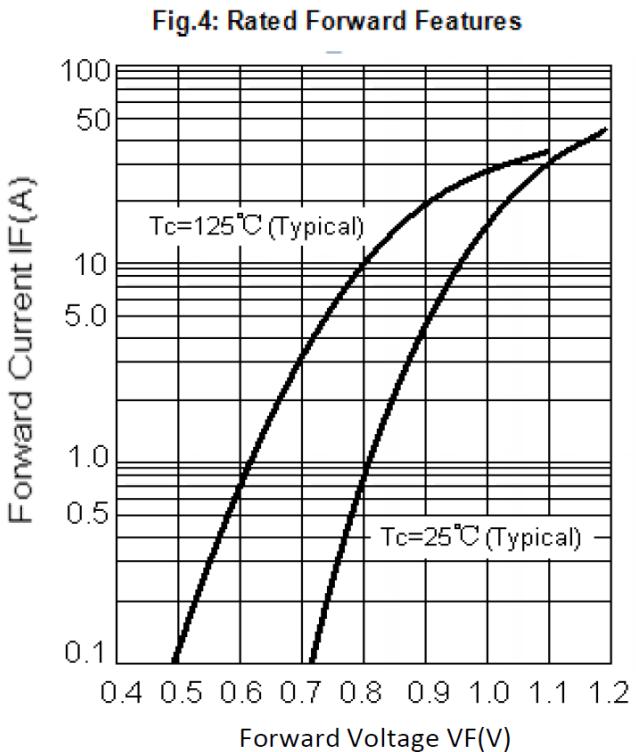
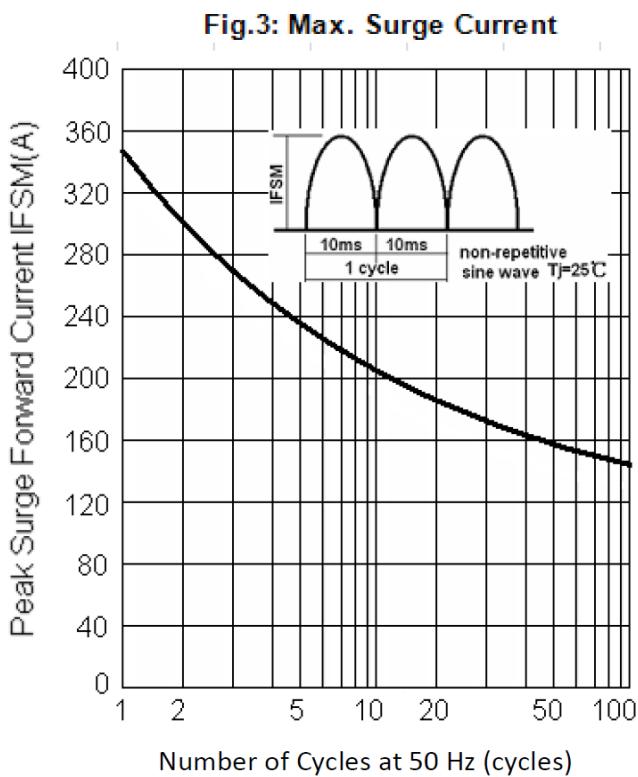
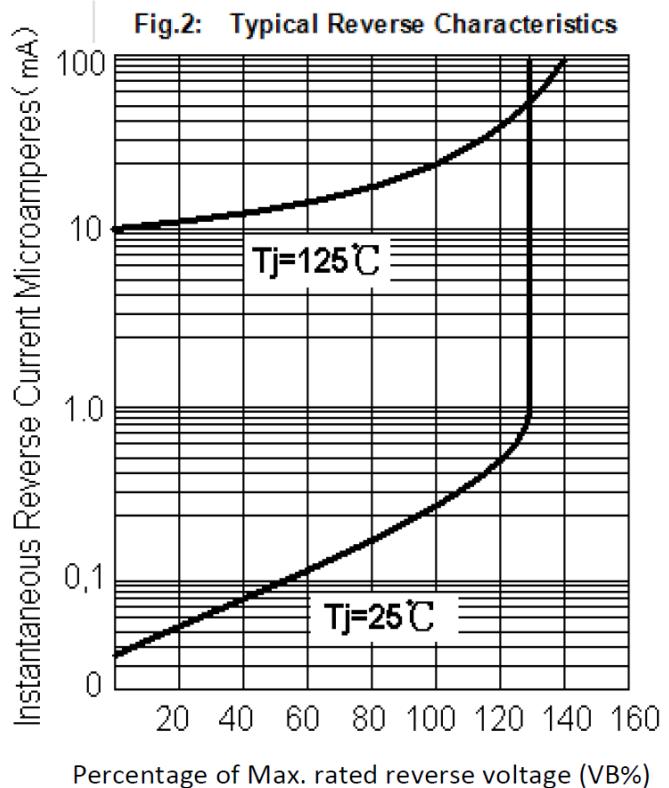
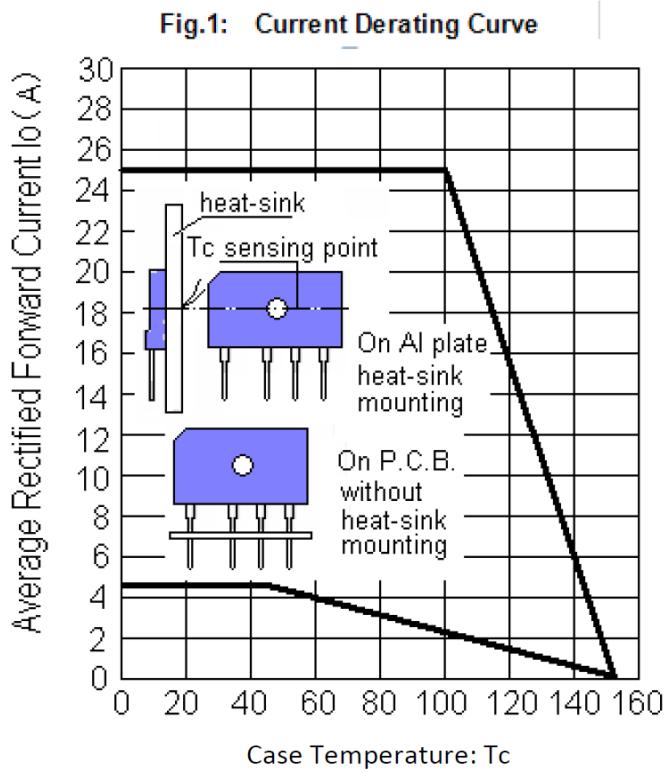
Electrical characteristics at T_A = 25 °C, unless otherwise specified

Resistive load, single phase, half sine wave, 60 Hz.

For capacitive load derate current by 20%.

Parameter	Symbol	Conditions	GBJ25B	GBJ25D	GBJ25G	Unit
Maximum average forward rectified current	I _O	T _C = 98 °C T _A = 25 °C	25 ⁽¹⁾ 4.5 ⁽²⁾	25 ⁽¹⁾ 4.5 ⁽²⁾	25 ⁽¹⁾ 4.5 ⁽²⁾	A
Maximum forward surge current	I _{FSM}	8.3 ms pulse width, single pulse sine-wave, rated load, T _j = 25 °C	350	350	350	A
Maximum forward voltage	V _F	I _F = 12.5 A	1.05	1.05	1.05	V
Max. reverse current leakage at rated DC blocking voltage	I _R	T _A = 25 °C T _A = 125 °C	5 500	5 500	5 500	µA
Insulation strength (Lead wire to case)	V _{dis}	AC Voltage: 1 minute, current leakage < 1 mA	2.5	2.5	2.5	kV
Fusing feature	I ² t	1ms ≤ t < 10ms, T _j =25 °C	300	300	300	A ² s
Thermal resistance	R _{θJA} R _{θJC}	without heatsink with stated size heatsink	22 ⁽²⁾ 1.0 ⁽¹⁾	22 ⁽²⁾ 1.0 ⁽¹⁾	22 ⁽²⁾ 1.0 ⁽¹⁾	°C/W
Mounting torque	T _{OR}		1.0 (0.8 Nm is recommended)			Nm

Remarks: (1) Install on PCB with stated size heat sink. In order to reach excellent heat dissipation performance, please coat thermal conductive silica gel in moderation, use M3 screw to screw up. Recommended heatsink size: 12.4*15.2*12.8 cm.
(2) Install on PCB without heatsink.



Package dimensions and terminal configuration

Product is marked with part number and terminal configuration.

